

Characterizing and Predicting Stress and Structural Relaxation in Glass

^aKevin T. Strong Jr, ^bBrenton Elisberg, ^bRyan D Jamison,
Tom Buchheit and ^cKevin G Ewsuk

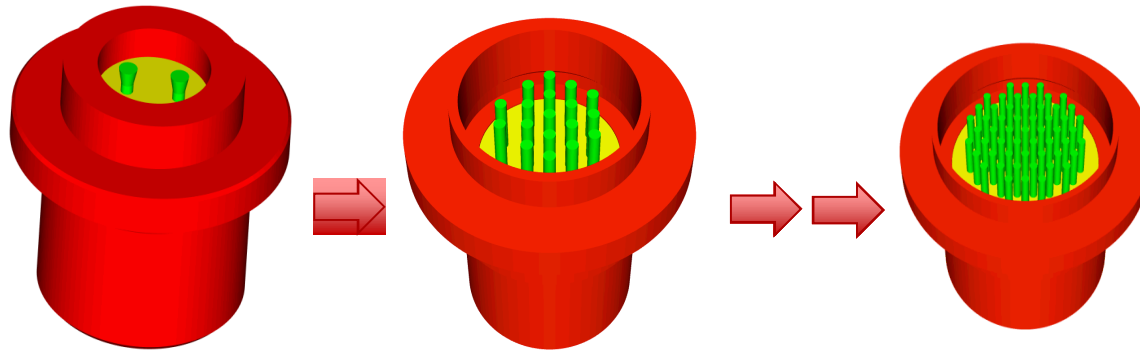
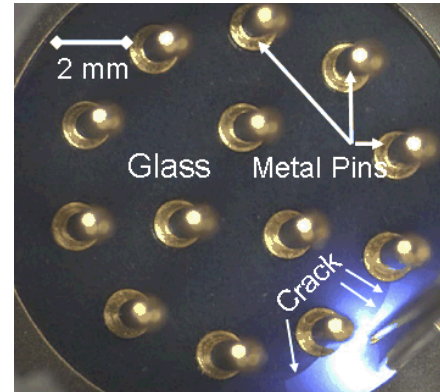
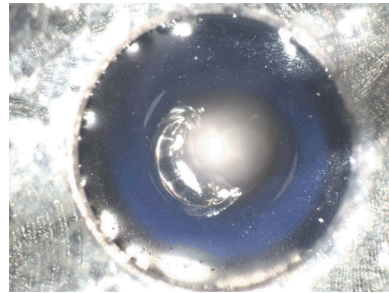
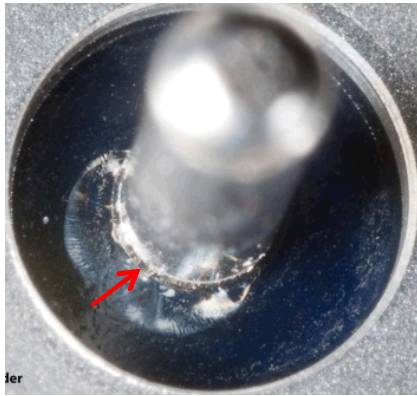
FFAG7

Monday, July 3, 2017

Outline

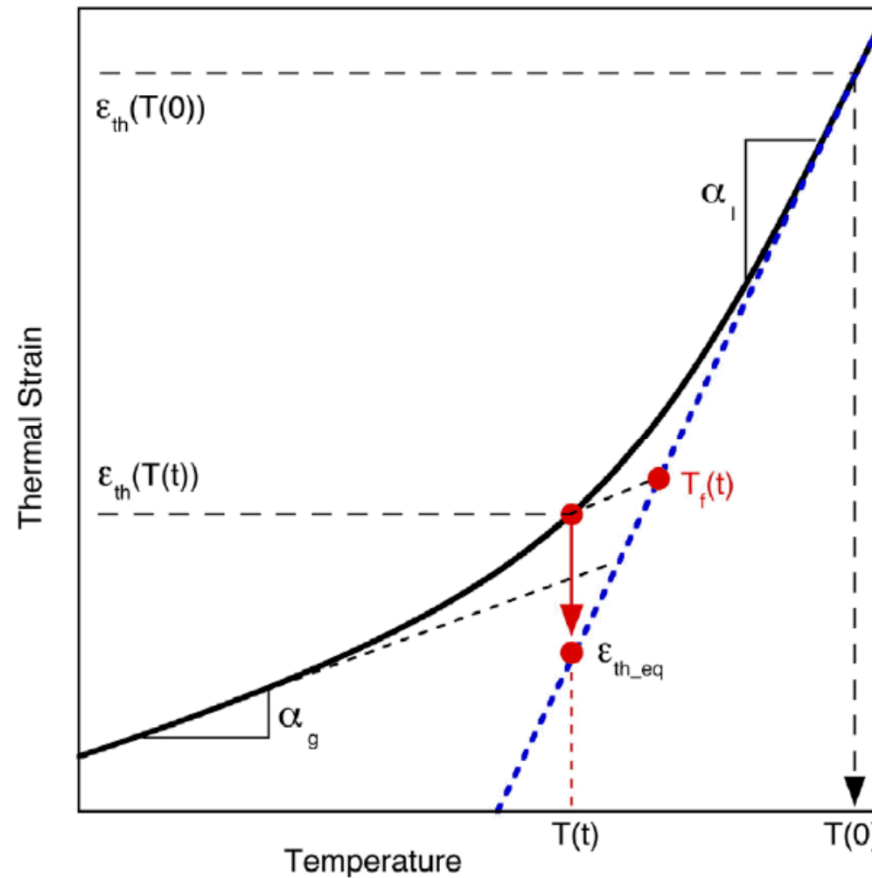
- Motivation
- Approach
- Model Calibration Experiments
- Model Validation
- Current Applications
- Conclusions

Motivation – Glass to Metal Seals

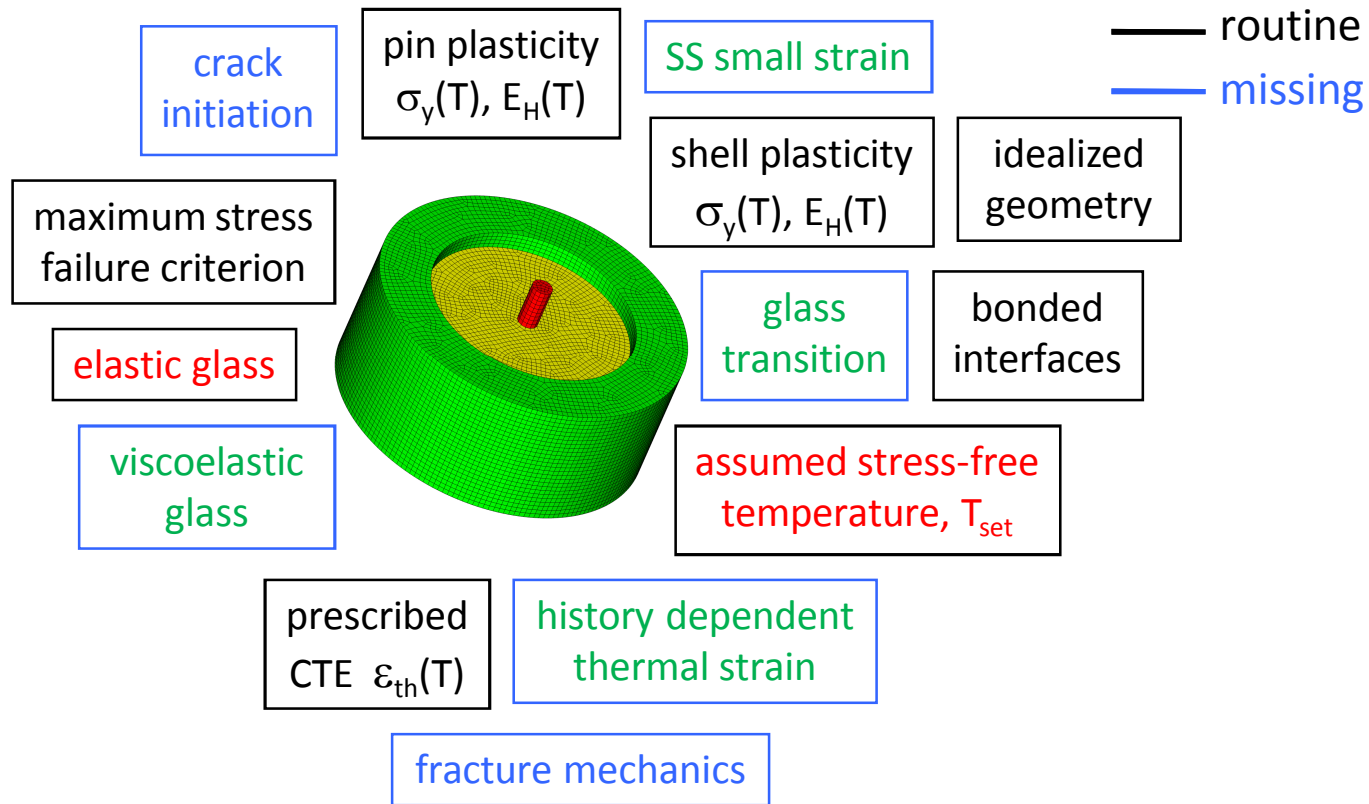


Higher fidelity stress modeling is needed to address shrinking performance margin in more complex designs

Background – Structural Relaxation



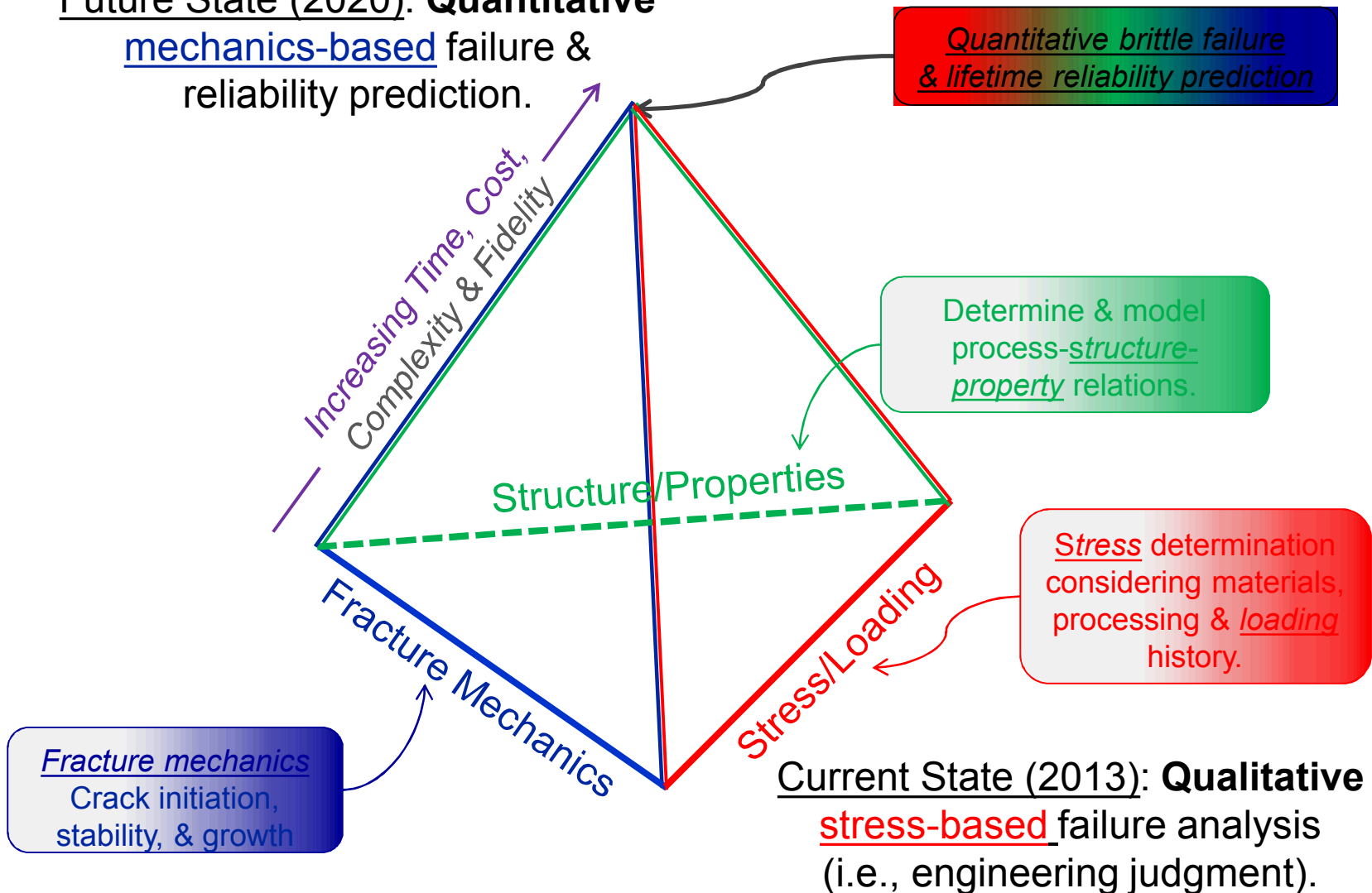
Finite Element (FE) Modeling Predicts Residual Stress In Glass-to-Metal Seals



Higher fidelity stress modeling is possible with improved materials behavior models

BrittMAPP – Brittle Materials Assurance Predictability Program

Future State (2020): **Quantitative**
mechanics-based failure &
reliability prediction.



Simplified Potential Energy Clock (SPEC) Model

Journal of Non-Crystalline Solids 432 (2016) 545–555



Contents lists available at [ScienceDirect](#)

Journal of Non-Crystalline Solids

journal homepage: www.elsevier.com/locate/jnoncrysol



Characterization and calibration of a viscoelastic simplified potential energy clock model for inorganic glasses



Robert S. Chambers^{a,*}, Rajan Tandon^b, Mark E. Stavig^c

^a Engineering Sciences Center, Sandia National Laboratories, Albuquerque, NM 87185–0346

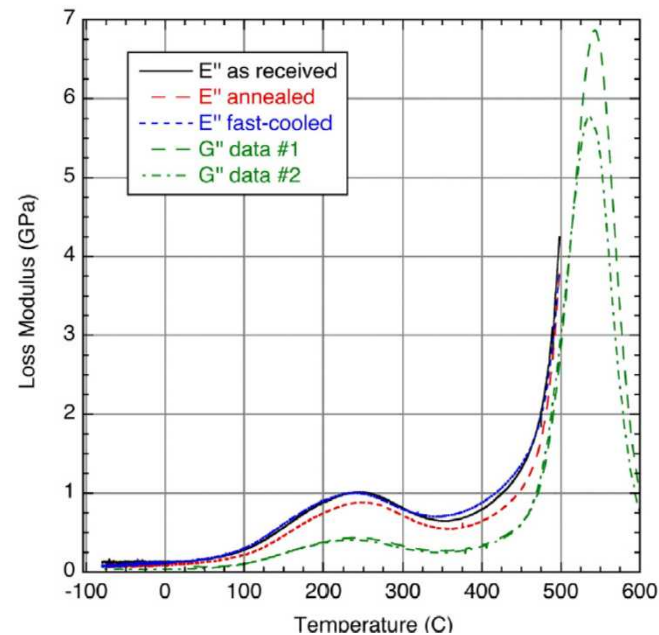
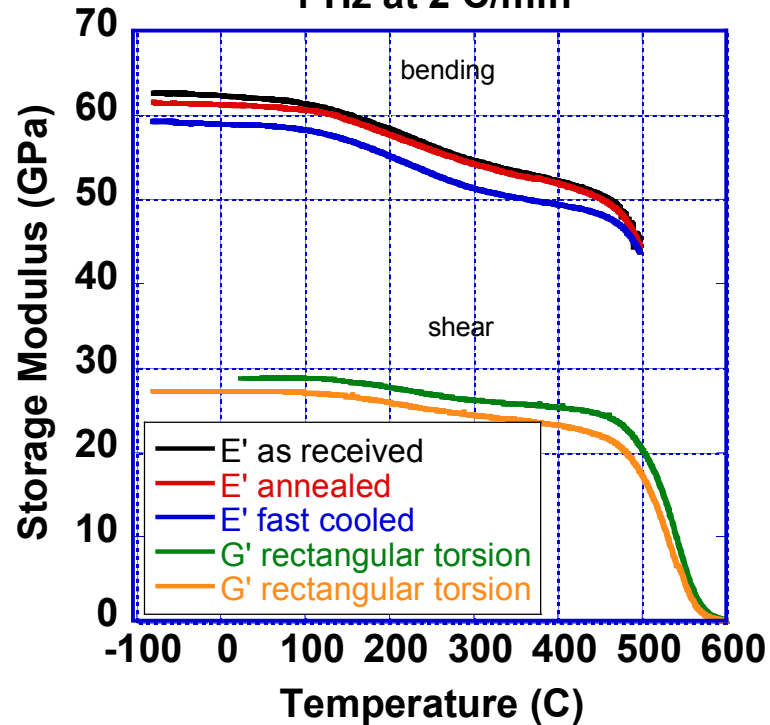
^b Analytical Technologies Department, Sandia National Laboratories, Albuquerque, NM 87185–0871

^c Materials Science and Engineering Center, Sandia National Laboratories, Albuquerque, NM 87185–0958

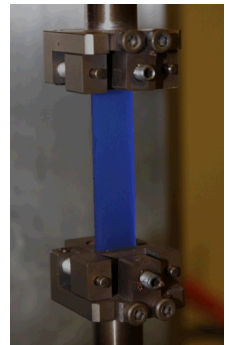
Dynamic Mechanical Analysis

Temperature Sweep

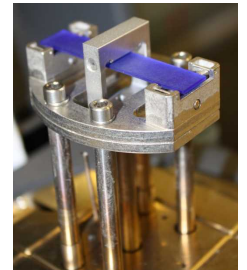
S8061 Temperature Sweep
1 Hz at 2 C/min



TA ARES
Rheometer

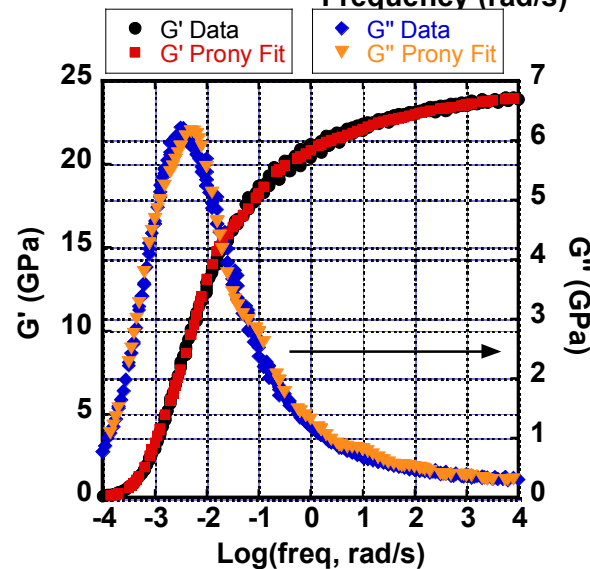
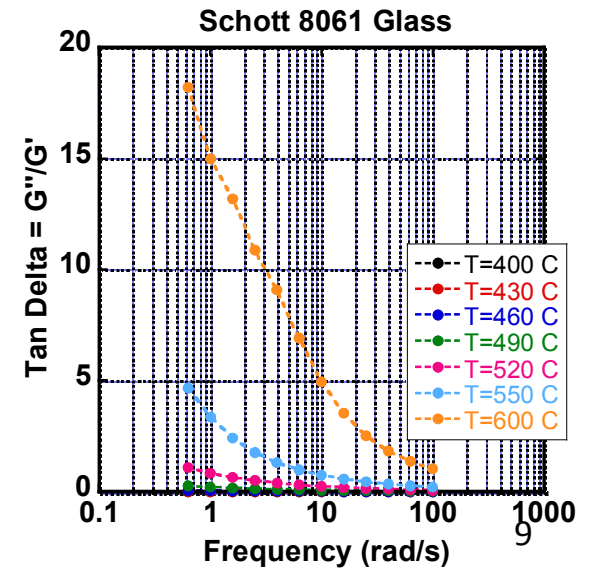
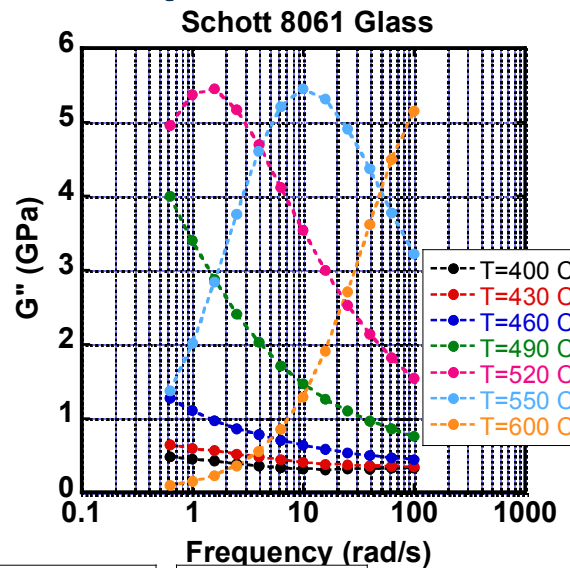
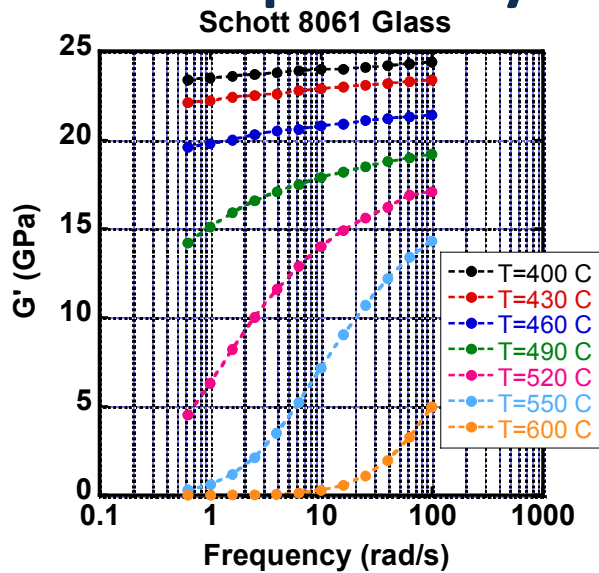


TA Q800 DMA

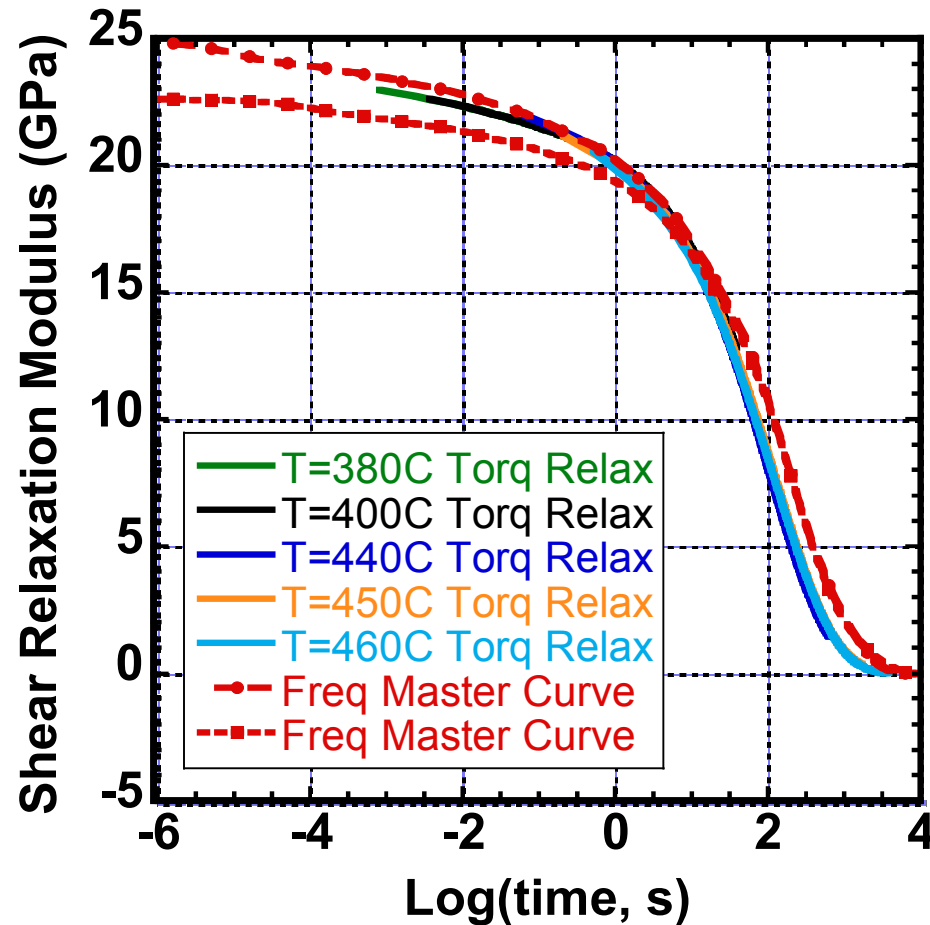


Dynamic Mechanical Analysis

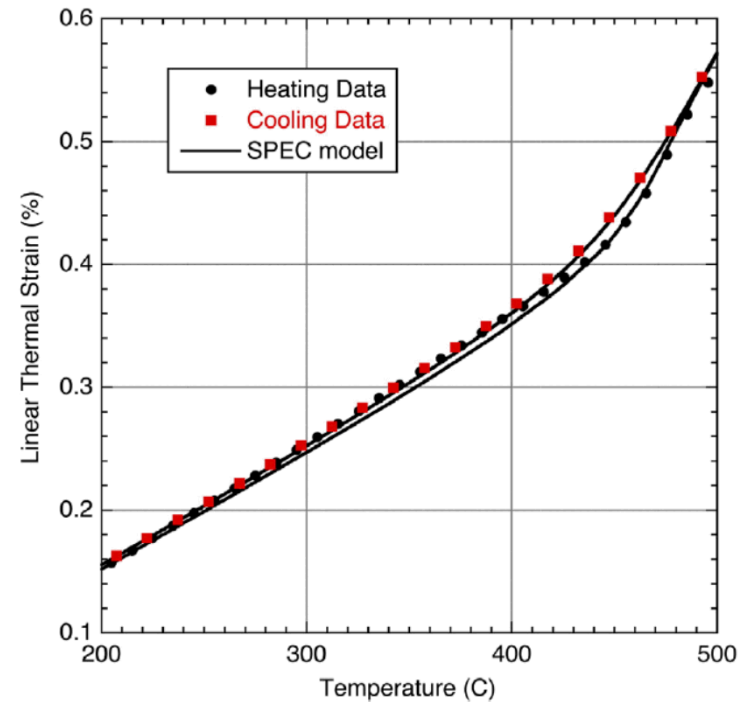
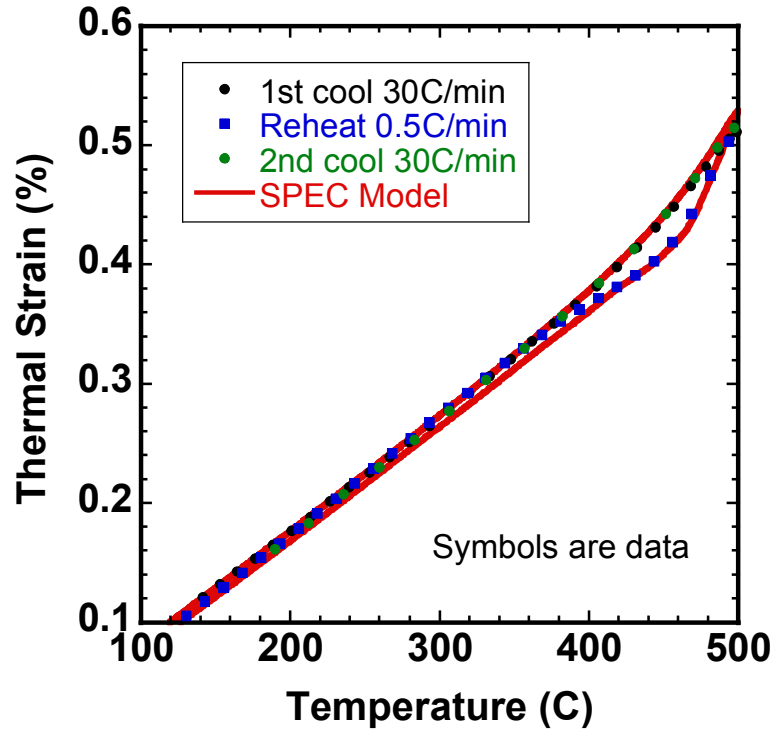
Frequency Sweep



Constructing time based master curve

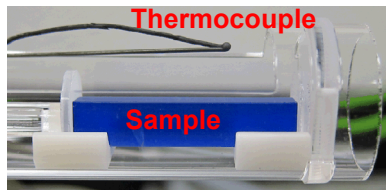
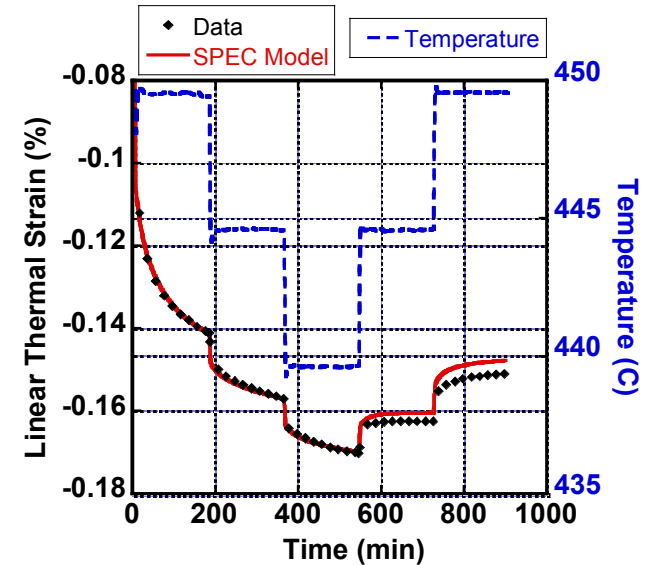
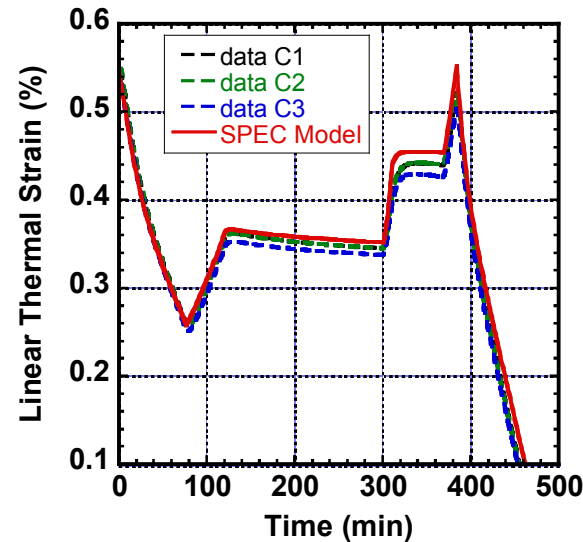
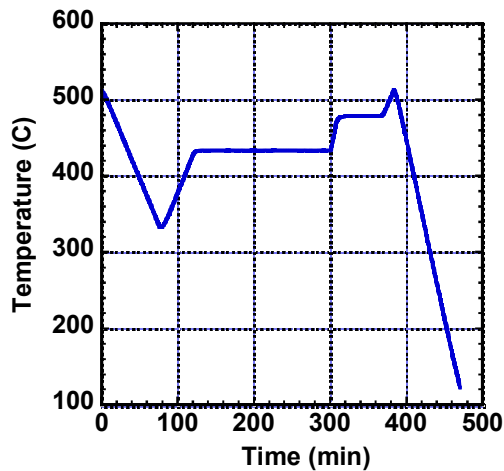


Model Calibration



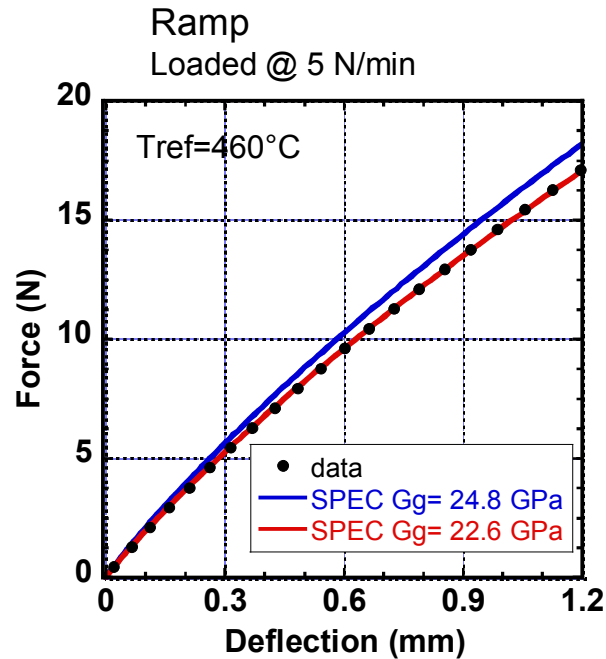
SPEC Model volume response adapted and calibrated to measure glass thermal strain

Model Validation – Complex Thermal History



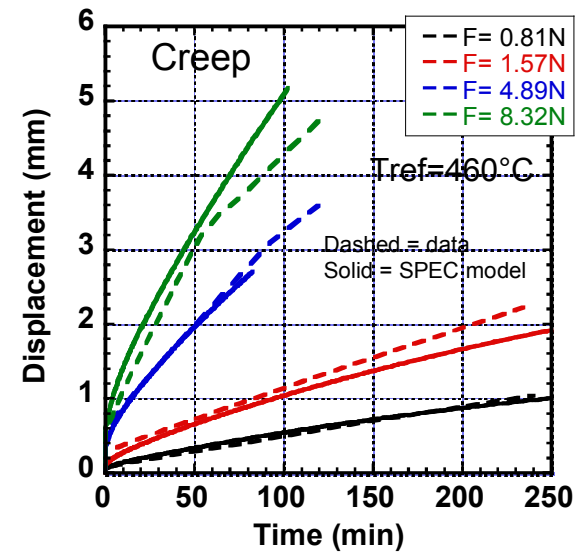
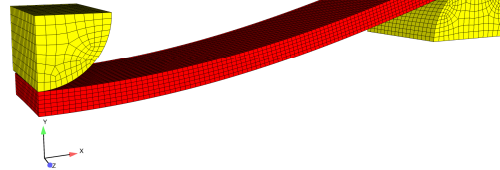
Netzsch Dilatometer

Model Validation – 3 – point bending



3-Pnt Bending Tests at T_g

55mm x 11mm x 1.1mm
beam

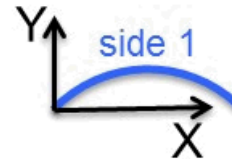


Characterizing Low Temp Creep

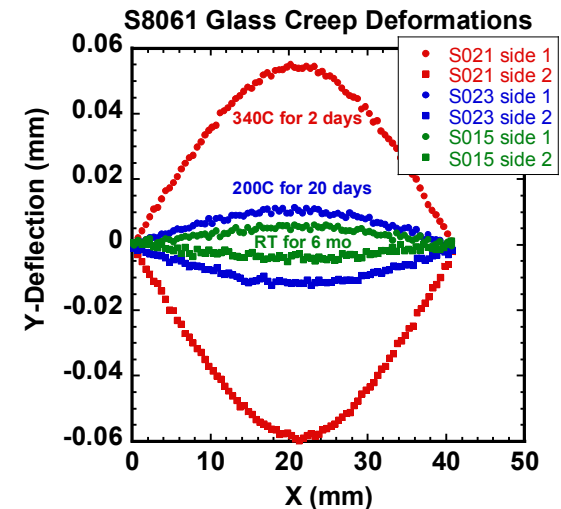
Three-point bend testing



T (°C)	Stress (psi)
340	4220
200	4220
20	4720

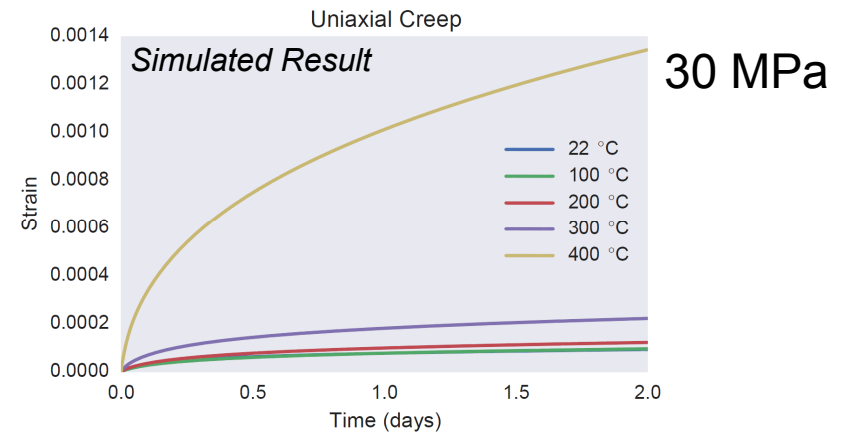
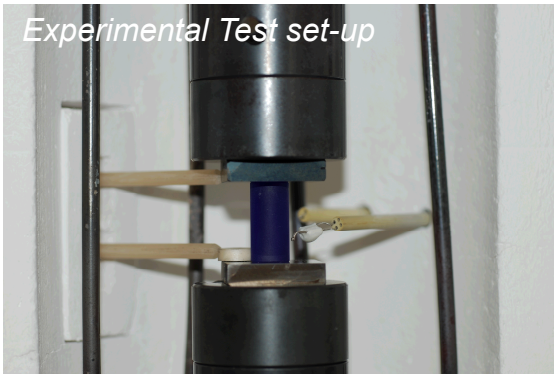


... Measurable creep 440°C
below Glass Transition

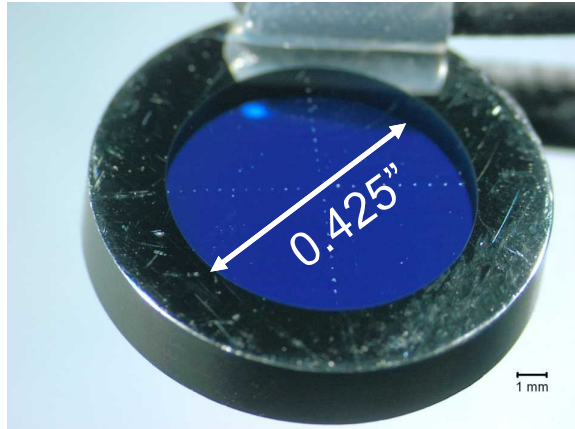


Compression creep testing

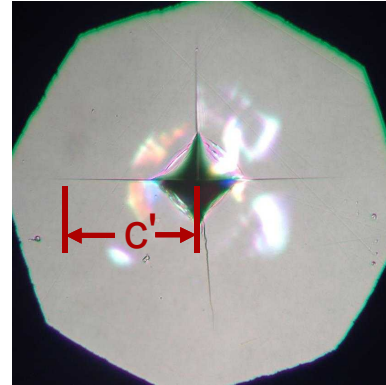
Experimental Test set-up



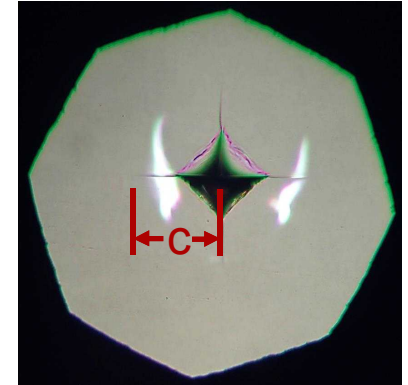
Model Validation: stress mapping by indentation crack measurements



GtoM seal test geometry



Polished Annealed Block
avg. $c \approx 92 \mu\text{m}$



Indent on test geometry
glass (not near SS shell)
avg. $c \approx 55 \mu\text{m}$

$$K_{Ic}' = \chi P/c^{3/2}$$

stressed
glass

unstressed
glass

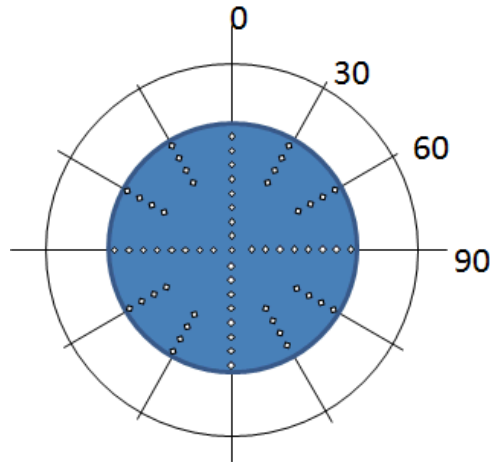
$$\sigma_r = \frac{-(K_I - K_{Ic}')}{1.12 \pi c^{1/2}}$$

*Derived from indentation fracture
mechanics concepts*

e.g. Lawn Fracture of Brittle Solids (1993)

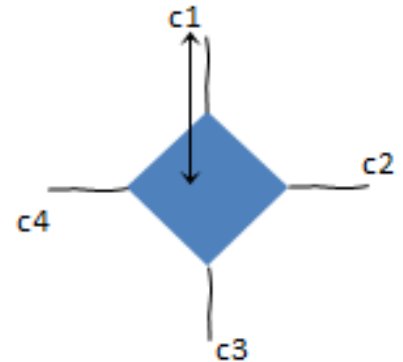
Model Validation: stress mapping by indentation crack measurements

Indentation locations



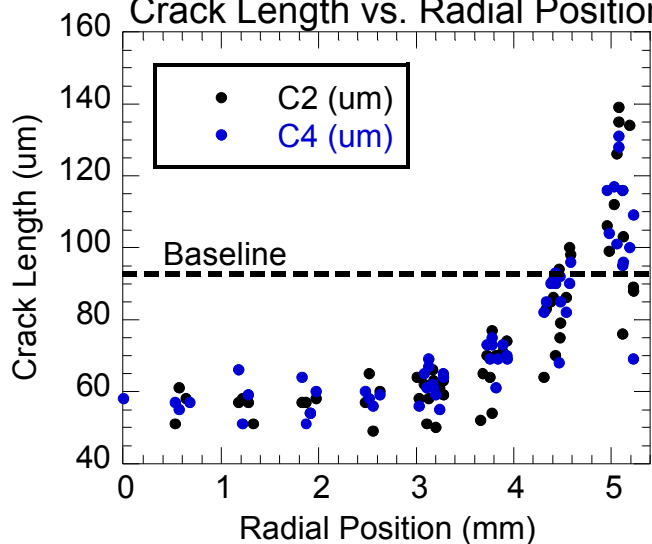
Radial Component
c1 and c3

Tangential Component
c2 and c4



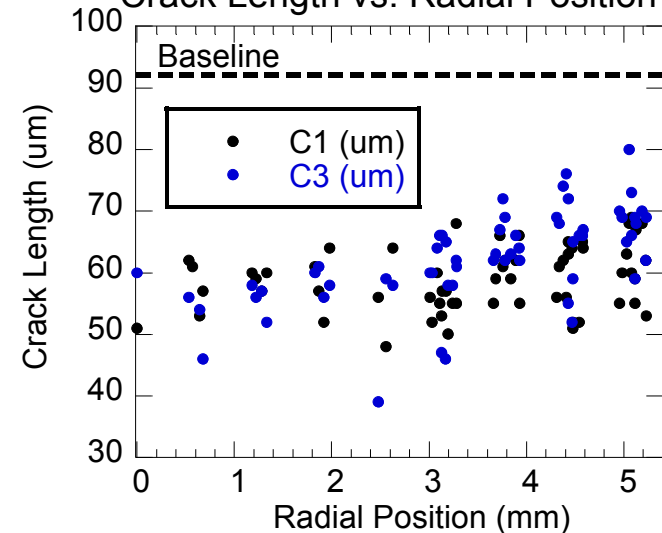
Radial Component

Crack Length vs. Radial Position



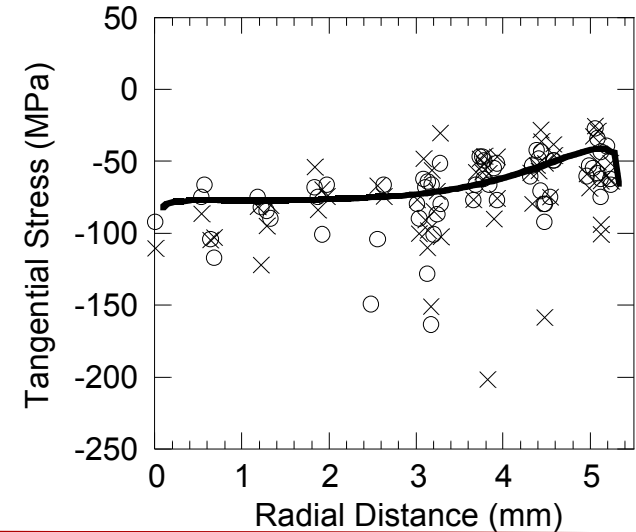
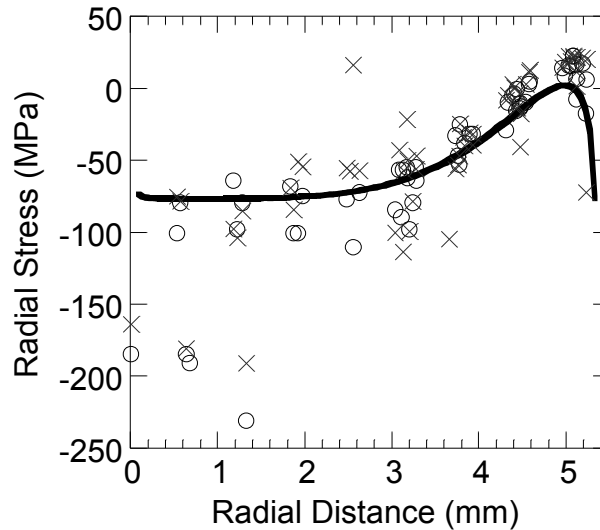
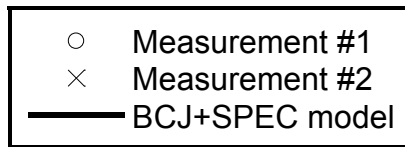
Tangential Component

Crack Length vs. Radial Position

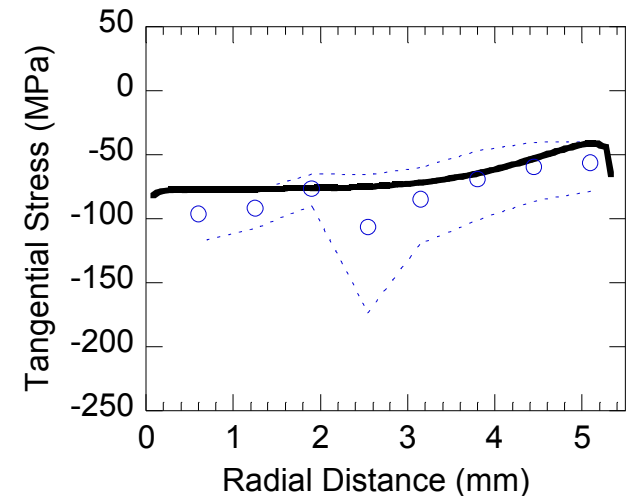
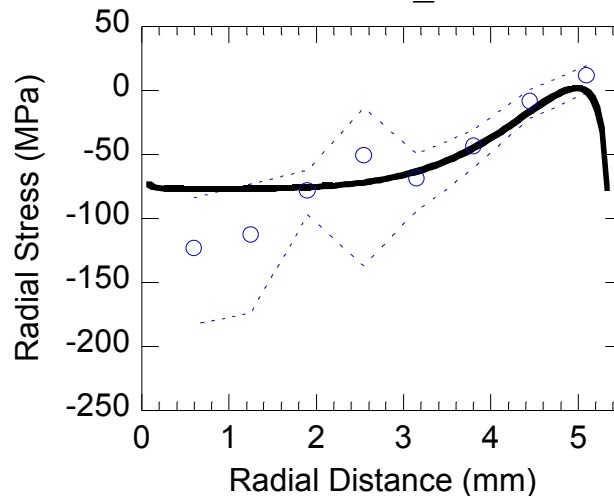
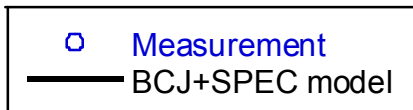


Measured data has been used to validate analysis

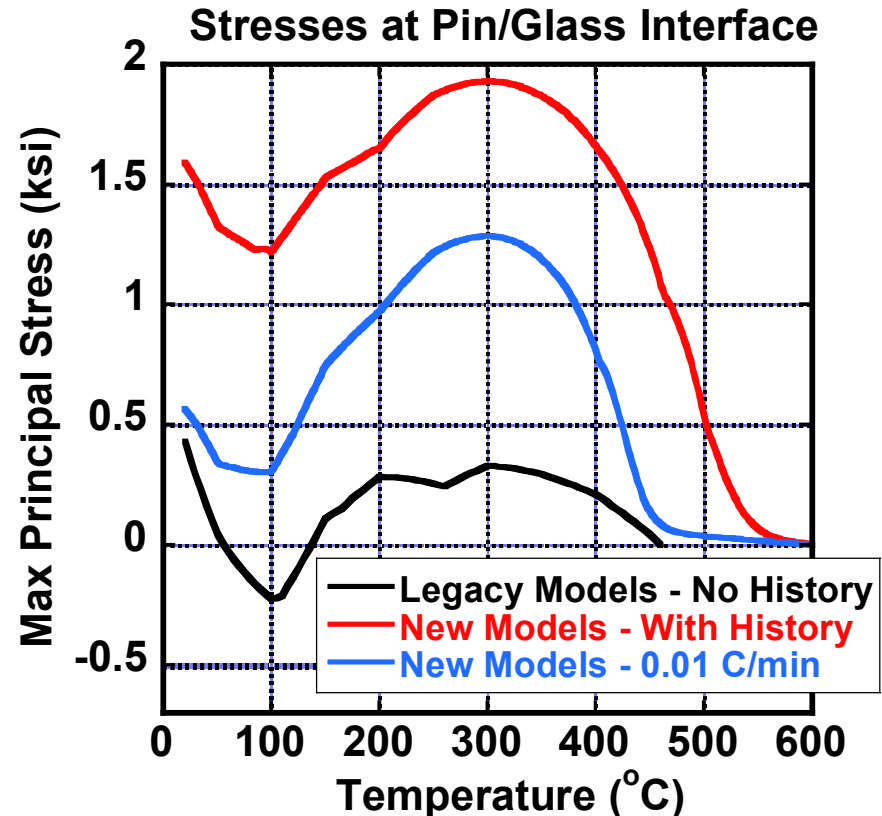
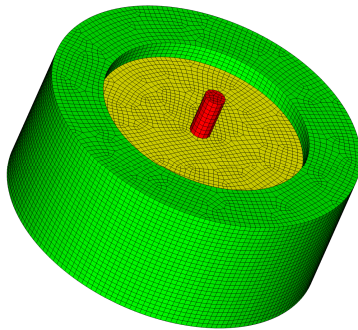
Direct Comparison



Averaged Result

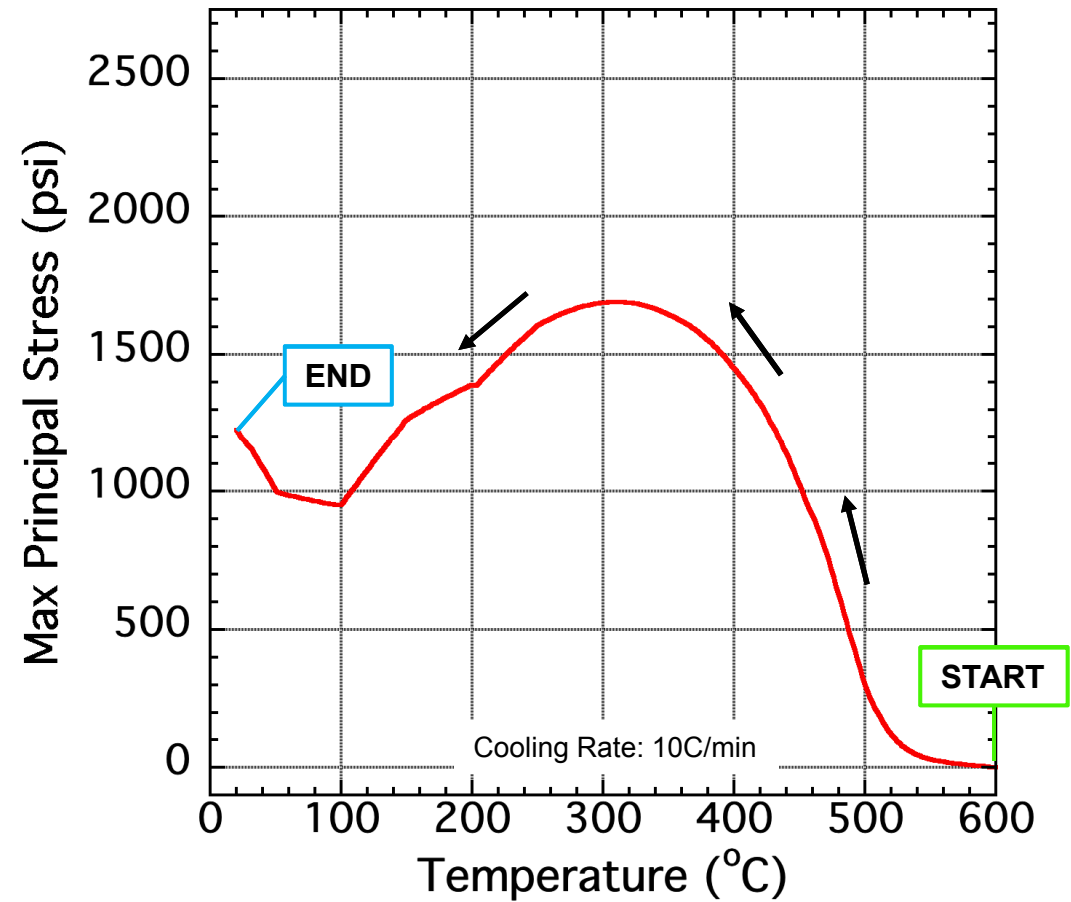
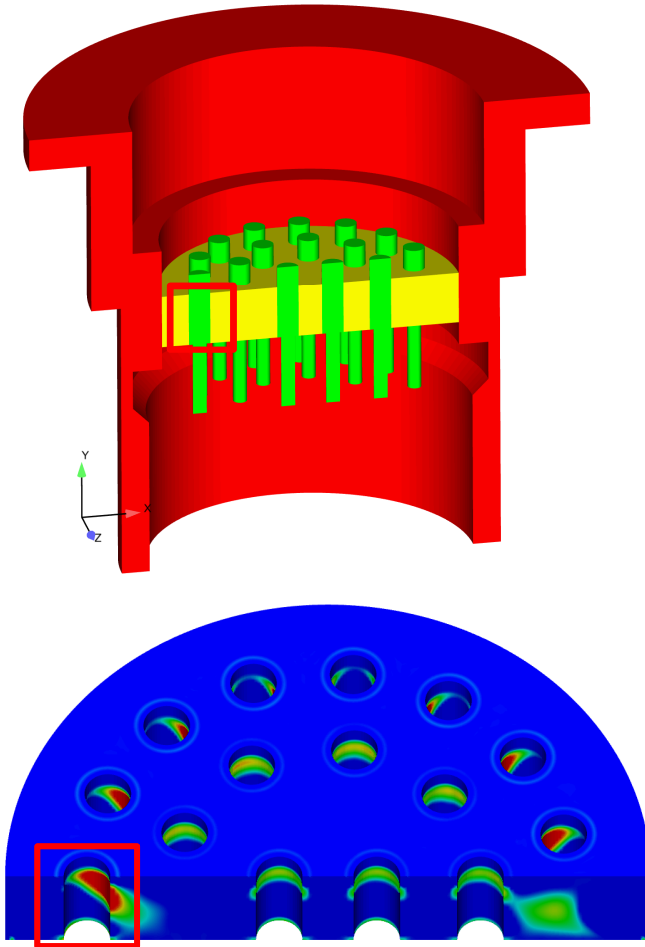


SPEC vs Purely Elastic Model

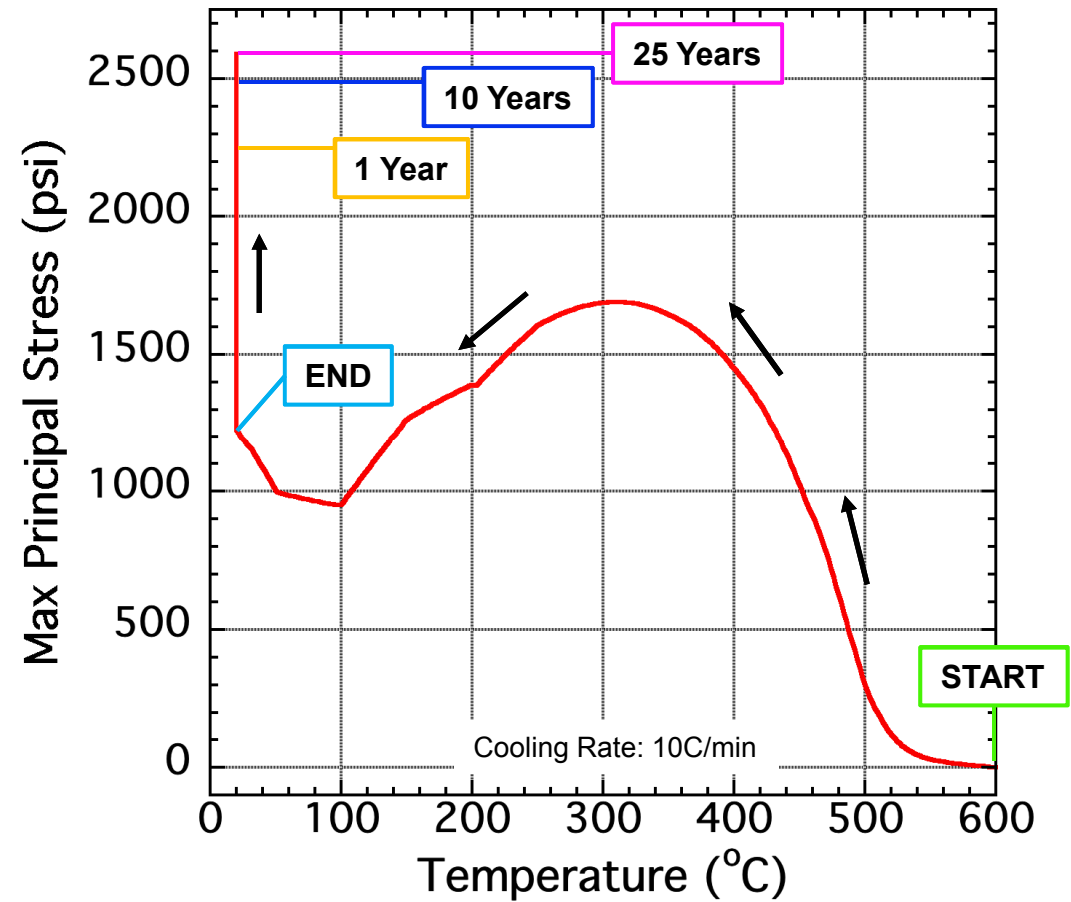
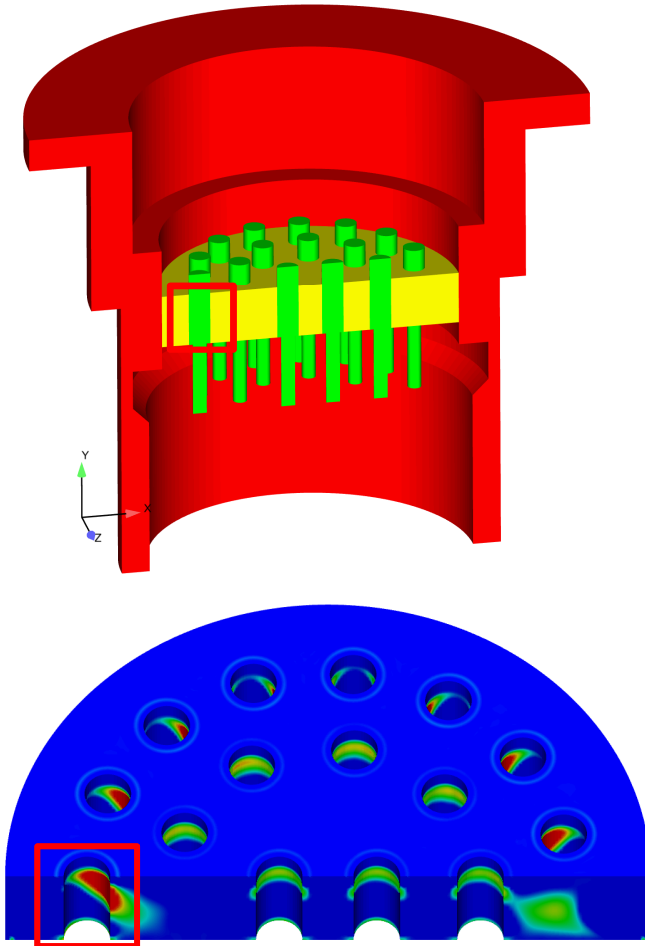


SPEC Model volume response adapted and calibrated to measure glass thermal strain

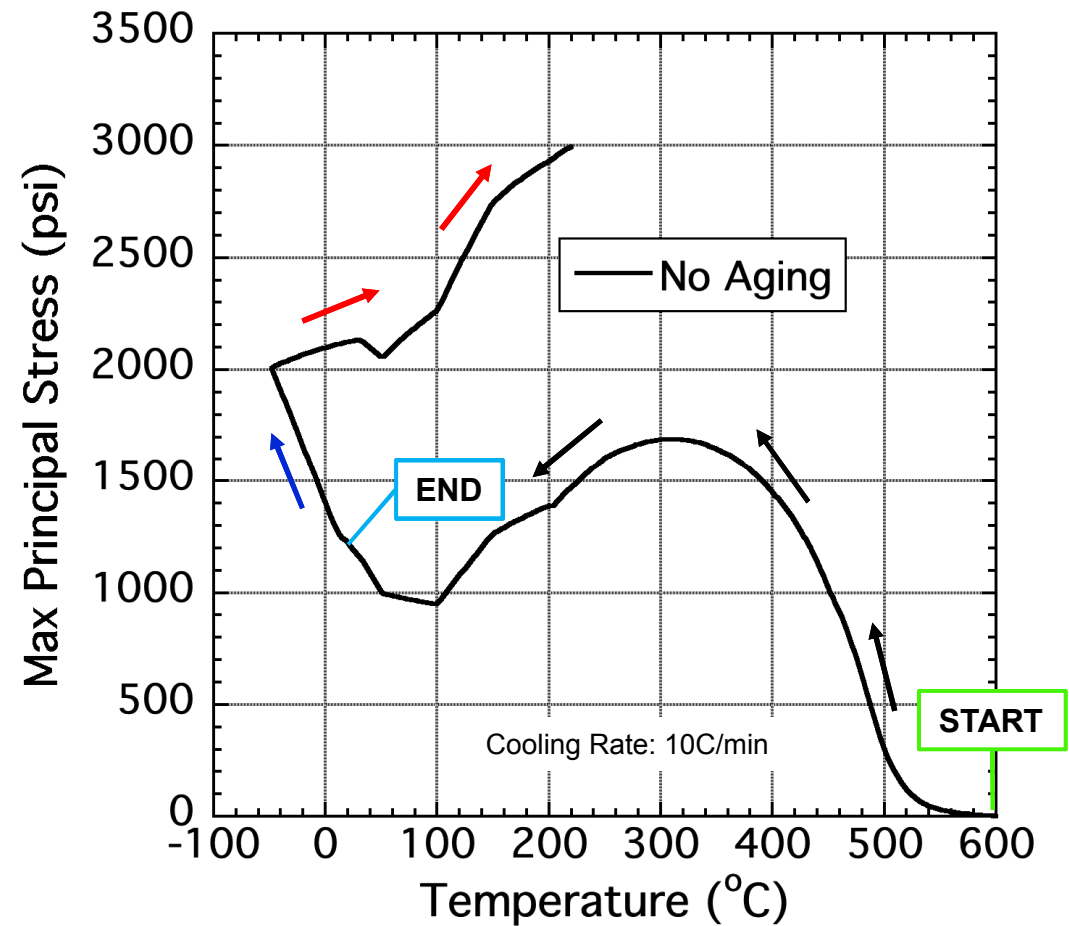
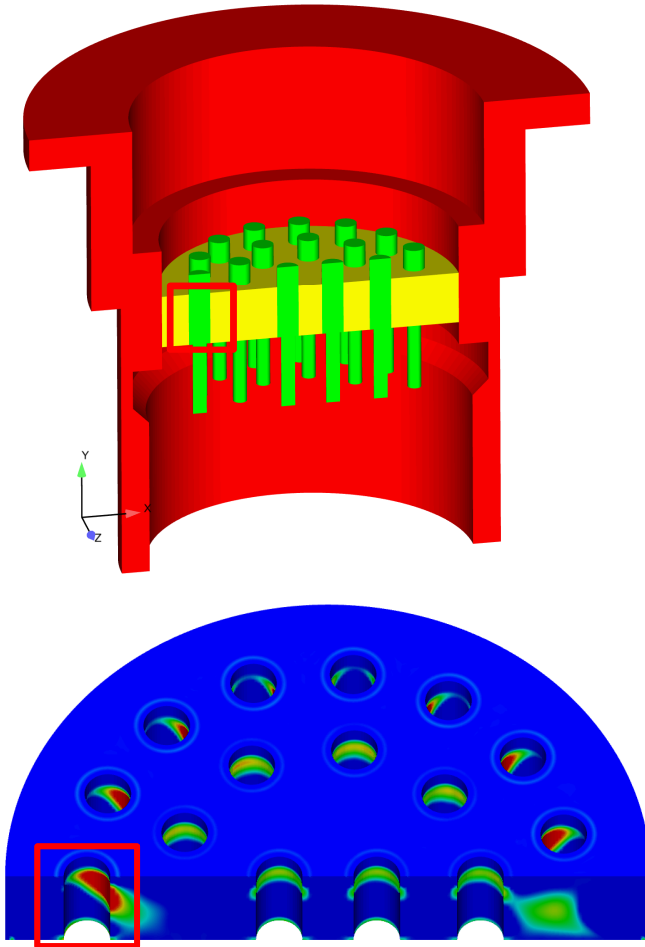
Investigate Complicated Designs



Aging of Compression Seal

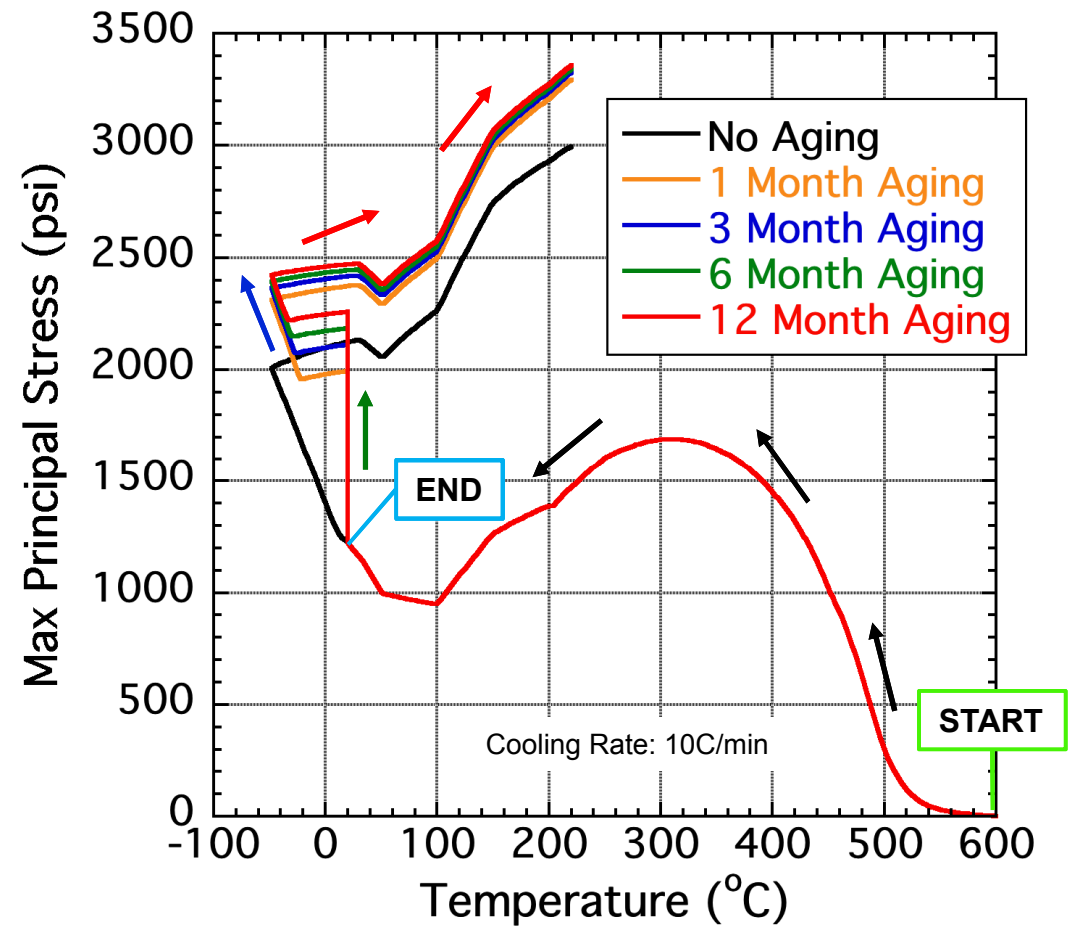
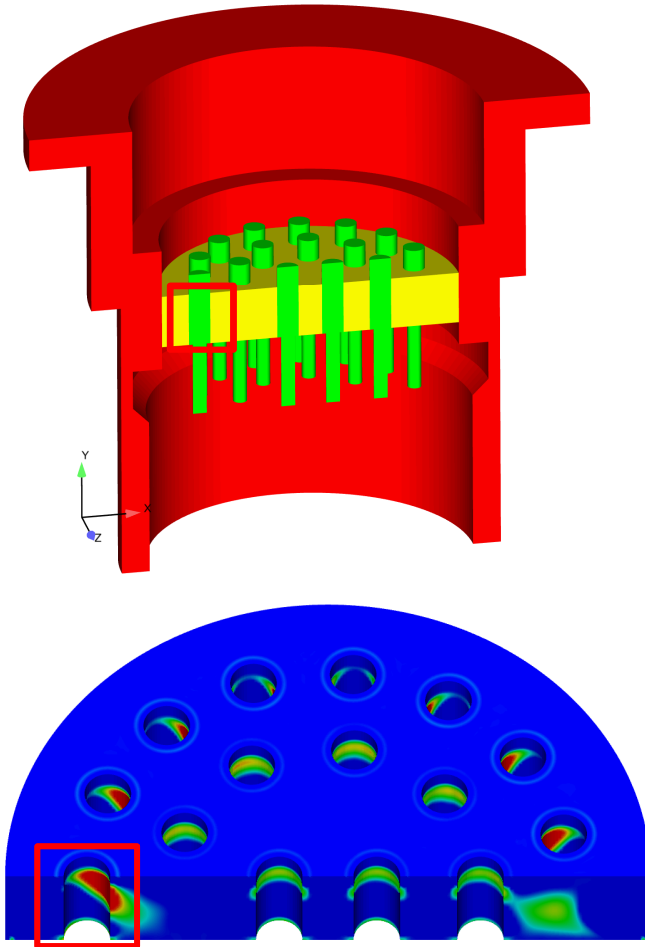


Residual Stress Due to Complex Thermal Histories



3 °C/min thermal cycle: -50 °C → 220 ° C

Residual Stress Due to Complex Thermal Histories



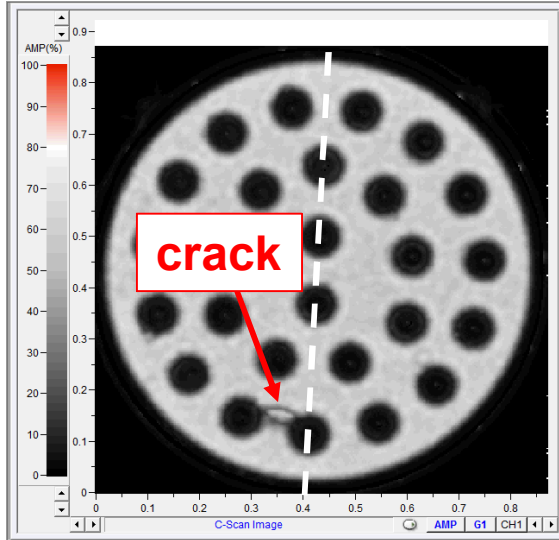
3 °C/min thermal cycle: -50 °C → 220 °C

Aging Testing

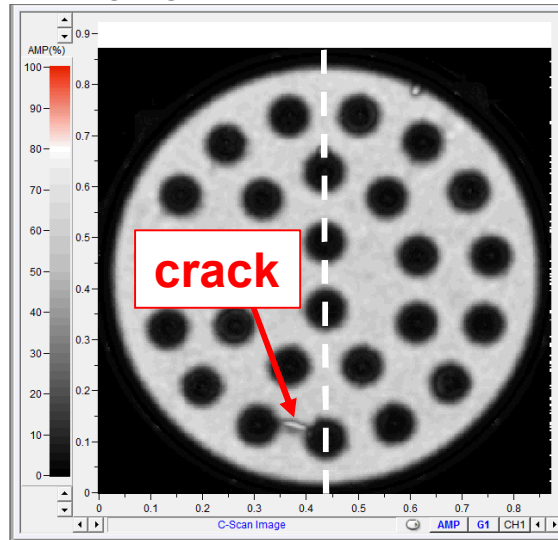
- 10 connectors tested after receiving from supplier
 - Approximately 2 days after manufacturing
- 10 connectors tested 6 months after receiving
- 10 cycles, then ultrasonic scan through glass thickness
 1. -50 °C → 150 °C
 2. -50 °C → 180 °C
 3. -50 °C → 200 °C
 4. -50 °C → 220 °C (oven low/high limits)
- 10/10 connectors tested shortly after receiving did not crack after all thermal cycles.
- 7/10 shells tested 6 months after receiving did not crack after the cycles.
 - **3/10 cracked after the -50 °C → 220 °C thermal cycles.**

Ultra Sound after 220 °C cycle

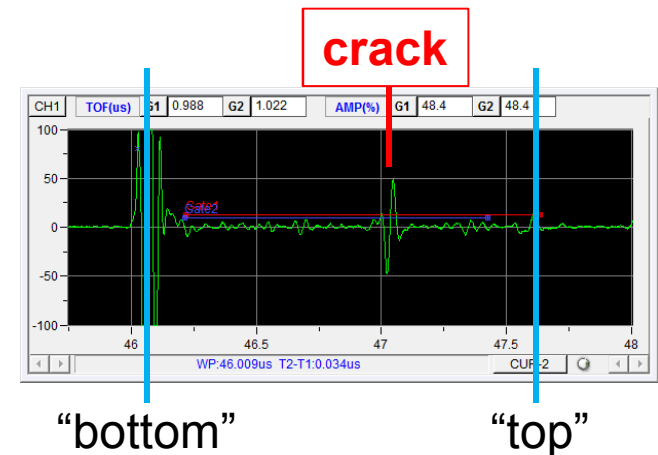
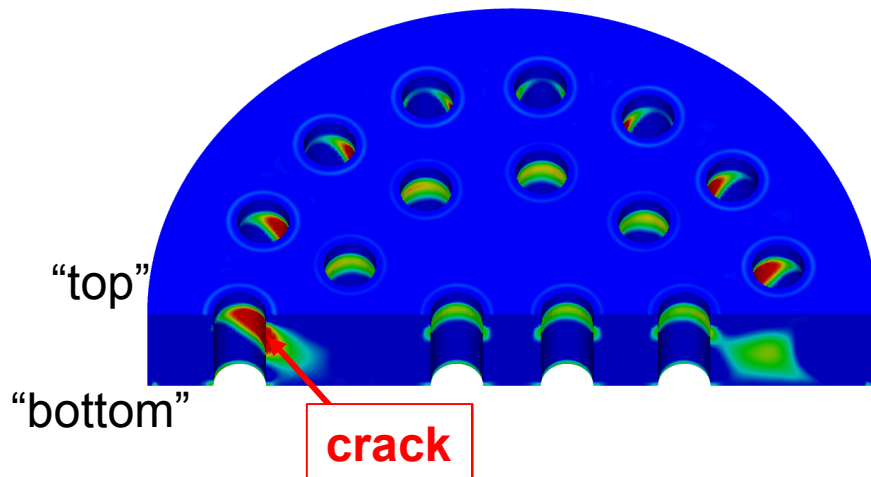
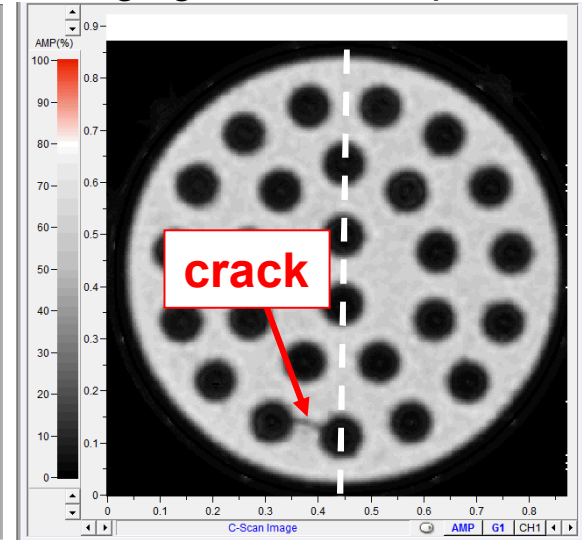
Imaging at Crack Depth #1



Imaging at Crack Depth #2

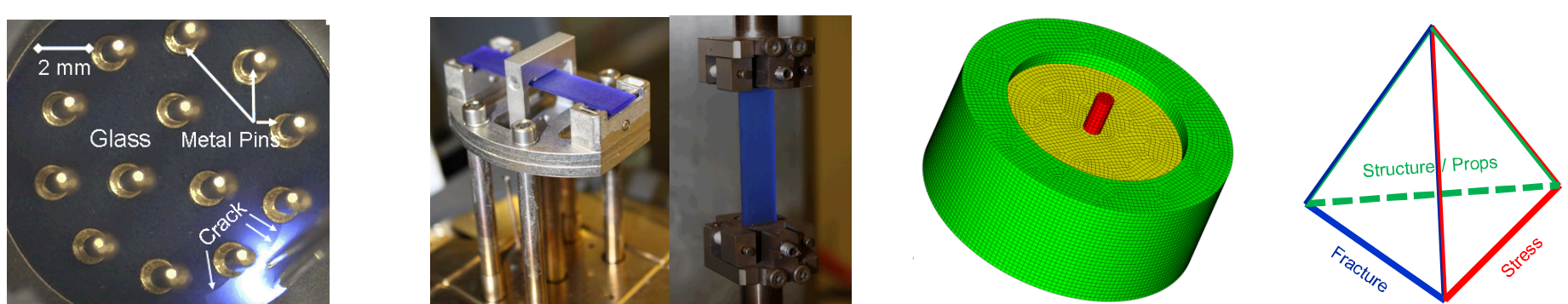


Imaging at Crack Depth #3



Conclusions

- SPEC model can predict glass response with engineering accuracy
- FEA predictions and data suggest that even short amounts of time may be changing the stress state of the hermetic seal.
- More experiments are necessary to validate long term aging predictions of the SPEC model.
 - FEA can help determine what experiments will be most useful.



Acknowledgements

- Thomas Buchheit
- Clay Newton
- Raj Tandon
- Bob Chambers
- Mark Stavig
- Scott Reedy

